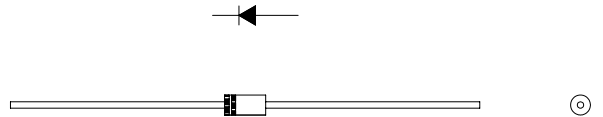


FRD Type :11DF2

OUTLINE DRAWING

FEATURES

- * Miniature Size
- * Ultra - Fast Recovery
- * Low Forward Voltage drop
- * Low Power Loss, High Efficiency
- * High Surge Capability
- * 200 Volts thru 400 Volts Types Available
- * 52mm Inside Tape Spacing Package Available



Maximum Ratings

Approx Net Weight:0.33g

Rating	Symbol	11DF2			Unit
Repetitive Peak Reverse Voltage	V _{RRM}	200			V
Non-repetitive Peak Reverse Voltage	V _{RSM}	220			V
Average Rectified Output Current	I _O	1.0	Ta=27℃ *1 Ta=63℃ *2	50Hz Half Sine Wave Resistive Load	A
RMS Forward Current	I _{F(RMS)}	1.57			A
Surge Forward Current	I _{FSM}	30	50Hz Half Sine Wave,1cycle, Non-repetitive		A
Operating JunctionTemperature Range	T _{jw}	- 40 to + 150			℃
Storage Temperature Range	T _{stg}	- 40 to + 150			℃

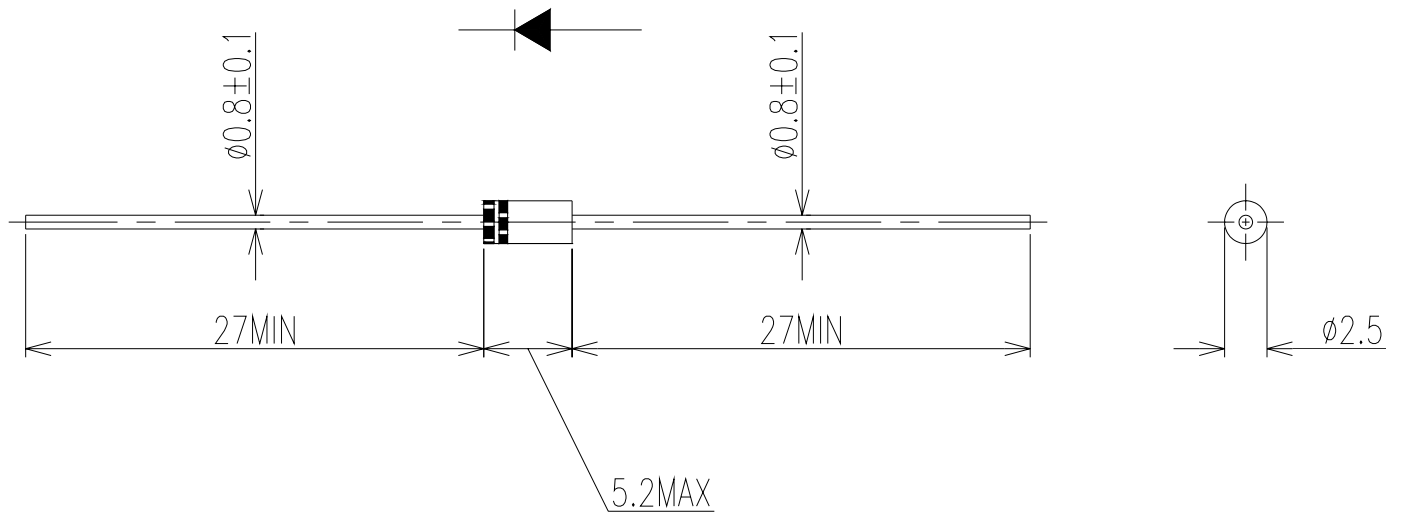
Electrical • Thermal Characteristics

Characteristics	Symbol	Conditions	Min.	Typ.	Max.	Unit
Peak Reverse Current	I_{RM}	Tj= 25°C, $V_{RM} = V_{RRM}$	-	-	10	μA
Peak Forward Voltage	V_{FM}	Tj= 25°C, $I_{FM} = 1.0A$	-	-	0.98	V
Reverse Recovery Time	t_{rr}	-di/dt=50A/μs, $I_{FM}=1A$, Ta=25	-	-	30	ns
Thermal Resistance	$R_{th(j-a)}$	Junction to Ambient	-	-	115	°C/W
		*1 : Without Fin *2 : P.C. Board mounted			81	

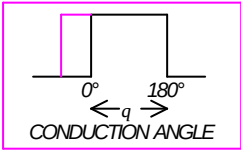
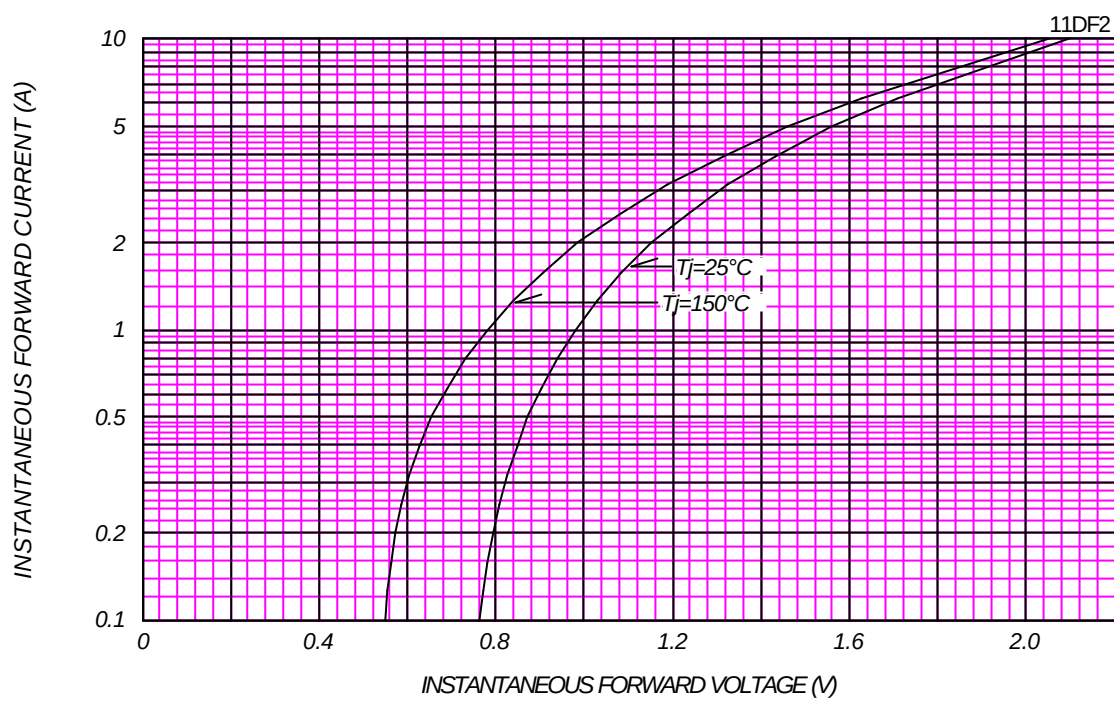
*1 : Without Fin or P.C. Board

*2 : P.C. Board mounted(L=8mm,Print Lands =10x10mm,Both Sides)

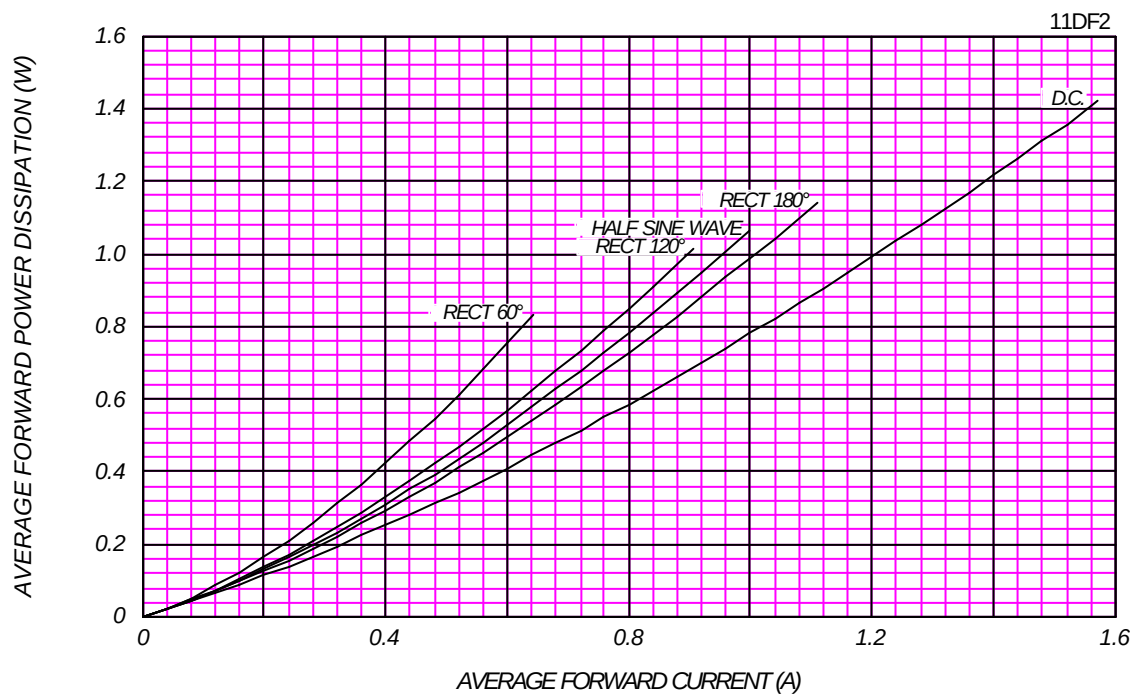
11DF2 OUTLINE DRAWING (Dimensions in mm)

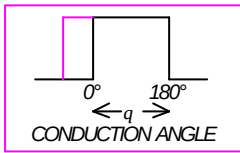


FORWARD CURRENT VS. VOLTAGE



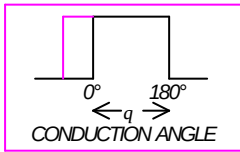
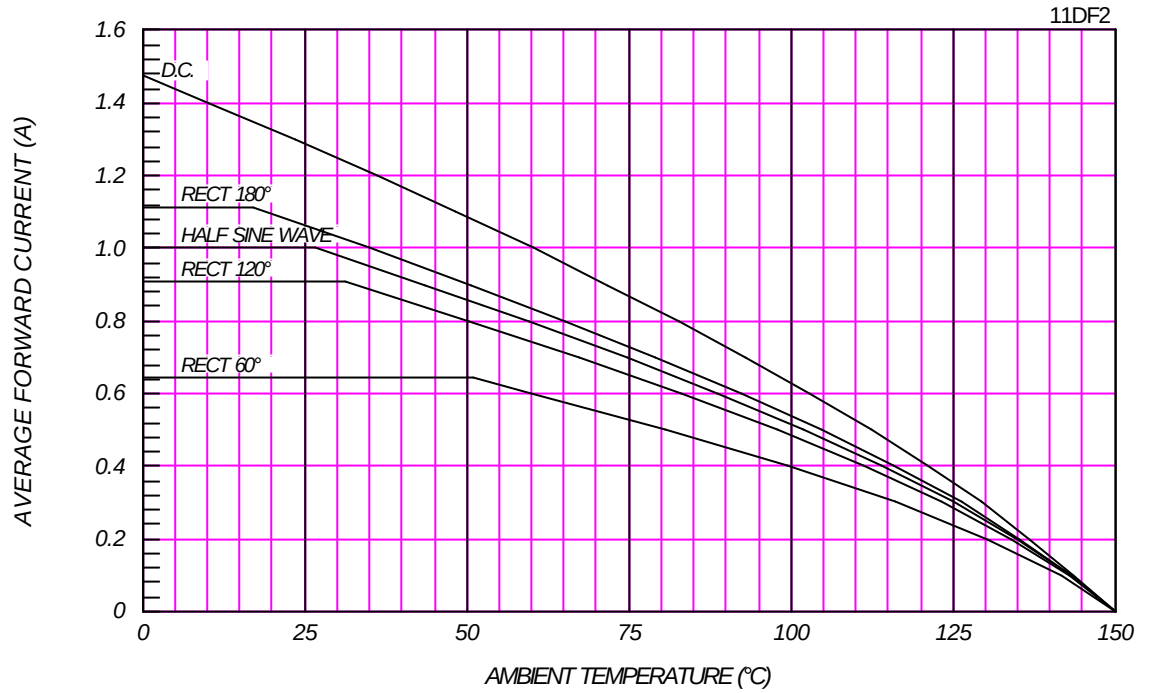
AVERAGE FORWARD POWER DISSIPATION





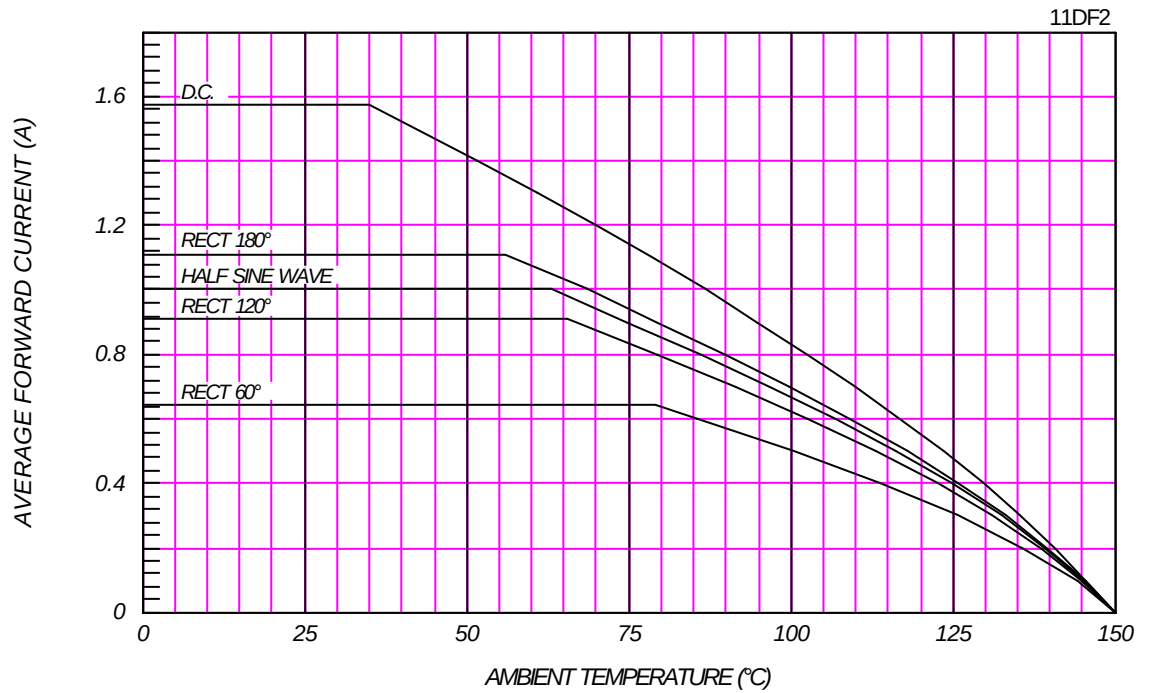
AVERAGE FORWARD CURRENT VS. AMBIENT TEMPERATURE

Without Fin or P.C. Board



AVERAGE FORWARD CURRENT VS. AMBIENT TEMPERATURE

P.C. Board mounted (L=8mm,Print Land=10×10mm,Both Sides)



SURGE CURRENT RATINGS

f=50Hz, Half Sine Wave, Non-Repetitive, No Load

11DF2

